

Technical Data Sheet

9/14/2010

2 Ton Epoxy®

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Description: Extremely strong, medium-cure, water-resistant clear adhesive that will self-level after application. Intended Use: Bonding parts in a structural environment or potting electronic components and assemblies Product Cures without shrinking features: Cures at room temperature Good impact resistance Produces strong, rigid bond on metal, ceramics, wood, concrete, glass, or combinations Limitations: Store between 55° and 75 F for optimum results. Keep from freezing. Technical data should be considered representative or typical only and should not be used for specification purposes. Typical Physical **TESTS CONDUCTED** Cured 7 days @ 75° F **Properties:** Thermal Conductivity ASTM C 177 Adhesive Tensile Lap Shear[GBS] 2,250 psi @ 0.010" bondline Dielectric Strength, volts/mil ASTM D 149 11,000 psi **Compression Strength** Compressive Strength ASTM D 695 600 volts/mil **Dielectric Strength** Cured Hardness Shore D ASTM D 2240 Gap Fill Good Adhesive Tensile Shear ASTM D 1002 Impact Resistance 6.5 ft.-lb./in.(2) Service Temperature Dry, -40 °F to 200 °F Shore Hardness 83 Shore D Solids by Volume 100 Specific Volume 25.2 in.(3)/lb. **Tensile Elongation** 1% Tpeel 2-3 pli Uncured Color Clear **Fixture Time** 30-35 min. @ 72°F **Full Cure** 16 hrs. **Functional Cure** 2 hrs. @ 72°F Mix Ratio by Volume 1:1 Resin/Hardener Mix Ratio by Weight 1.2:1 Resin/Hardener **Mixed Density** 9.17 lbs/gal.: 1.10 gm/cc Mixed Viscosity 8,000 cps Working Time 8-12 min. (28 gm @ 72 °F) Surface Clean surface by solvent-wiping any deposits of heavy grease, oil, dirt, or other contaminants. Surface can also be cleaned with industrial cleaning equipment such as vapor phase degreasers or hot aqueous baths. If working with metal, Preparation: abrade or roughen the surface to significantly increase the microscopic bond area and increase the bond strength. ---- Proper homogenous mixing of resin and hardener is essential for the curing and development of stated strengths. ----Mixing Instructions: 25 ML DEV-TUBE 1. Squeeze material into a small container the size of an ashtray. 2. Using mixing stick included on Dev-tube handle, vigorously mix components for one (1) minute. 3. Immediately apply to substrate. 50 ML/400ML/490 ML CARTRIDGES 1. Attach cartridge to Mark V ™ [50ml] 400ml manual or pneumatic dispensing systems. 2. Open tip. 3. Burp cartridge by squeezing out some material until both sides are uniform (ensures no air bubbles are present during mixing). 4. Attach mix nozzle to end of cartridge. 5. Apply to substrate.

Application

| Application Instructions: | Apply mixed epoxy directly to one surface in an even film or as a bead. Assemble with mating part within recommended working time. Apply firm pressure between mating parts to minimize any gap and ensure good contact (a small fillet of epoxy should flow out the edges to display adequate gap fill.) For very large gaps: Apply epoxy to both surfaces Spread to cover entire area OR make a bead pattern to allow flow throughout the joint Let bonded assemblies stand for recommended functional cure time prior to handling. CAPABILITIES: Can withstand processing forces Do not drop, shock load, or heavily load Full bond strength is reached in 16 hours. | | | |
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| Storage: | Store in a cool, dry place. | | | |
| Compliances: | None | | | |
| Chemical Resistance: | Chemical resistance is calculated w Acetic (Dilute) 10% Acetone Ammonia Corn Oil Cutting Oil Ethanol Gasoline (Unleaded) Glycols/Antifreeze | vith a 7 day, room tem Poor Fair Very good Excellent Excellent Poor Excellent Excellent Excellent | p. cure (30 days immersion) @ 75 % Hydrochloric 10% Isopropanol Kerosene Methyl Ethyl Ketone Mineral Spirits Motor Oil Sodium Hydroxide 10% Sulfuric 10% |) Poor Poor Excellent Poor Excellent Excellent Very good Poor |
| Precautions: | Please refer to the appropriate material safety data sheet (MSDS) prior to using this product. For technical assistance, please call 1-800-933-8266 FOR INDUSTRIAL USE ONLY | | | |
| Warranty: | Devcon will replace any material found to be defective. Because the storage, handling and application of this material is beyond our control, we can accept no liability for the results obtained. | | | |
| Disclaimer: | All information on this data sheet is based on laboratory testing and is not intended for design purposes. ITW Devcon makes no representations or warranties of any kind concerning this data. | | | |
| Order Information: | 14355 400 ml cartridge 14310 25 ml Dev-Tube™ 14360 9 lb. 14260 50 ml cartridge | | | |

